CLAIMS

1. A flux used for soldering,

the flux comprising: at least one selected from the group consisting of a fatty alcohol having one hydroxy group and being solid at 20°C and a fatty acid ester being solid at 20°C;

a liquid solvent having one or more and three or less hydroxy groups and being liquid at 20°C; and

a solid solvent having two or more and four or less hydroxy groups and being solid at 20°C,

the flux comprising no thixotropic agent or comprising 20.0 mass% or less of a thixotropic agent based on the entire flux, wherein

the flux comprises the fatty acid ester, and

the content of the fatty acid ester is 0.5 mass% or more and 45.0 mass% or less based on the entire flux.

2. The flux according to claim 1, wherein

the fatty alcohol is at least one selected from the group consisting of 1-dodecanol, 1-tetradecanol, 1-hexadecanol, 1-octadecanol, 1-eicosanol, and 1-docosanol.

3. The flux according to claim 1, wherein

the fatty acid ester is at least one selected from the group consisting of methyl stearate, ethyl stearate, and butyl stearate.

4. A solder paste comprising the flux according to claim 1, and a solder alloy powder.

5. A method for producing a joined structure in which a substrate and a joining part are joined together using the solder paste according to claim 4.